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Electronic Patent Application Submission

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Application ID: 10706468



Title of Invention:
SEMICONDUCTOR PACKAGE
WITH CHAMFERED CORNERS
AND METHOD OF

MANUFACTURING THE SAME

First Named Inventor: Sung Yang

Domestic/Foreign Application: Domestic Application

Filing Date: 2003-11-12

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Information Disclosure
Statement

Filing Type:

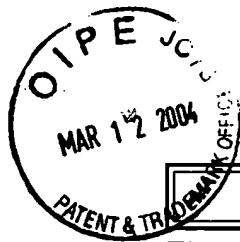
Confirmation number: 6744

Attorney Docket Number: AMKOR095A

Total Fees Authorized:

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TRANSMITTAL

Electronic Version v1.1
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Application Number:	10/706468	
Date:	2003-11-12	
First Named Applicant:	Sung Jin Yang	
Confirmation Number:	6744	
Attorney Docket Number:	AMKOR095A	
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Submitted by:	Elec. Sign.	Sign. Capacity
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney
Documents being submitted us-ids	Files ids2-usidst.xml us-ids.dtd us-ids.xsl	
Comments		

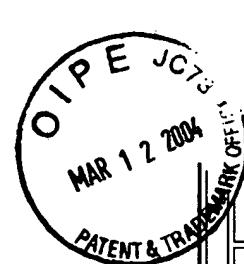


ELECTRONIC INFORMATION DISCLOSURE STATEMENT

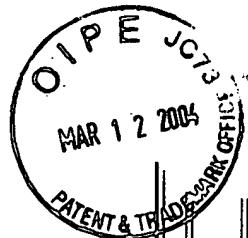
Electronic Version v18

Stylesheet Version v18.0

Title of Invention	SEMICONDUCTOR PACKAGE WITH CHAMFERED CORNERS AND METHOD OF MANUFACTURING THE SAME						
Application Number:	10/706468 						
Confirmation Number:	6744						
First Named Applicant:	Sung Yang						
Attorney Docket Number:	AMKOR095A						
Art Unit:	2811						
Search string:	(5221642 or 5250841 or 5252853 or 5258094 or 5266834 or 5273938 or 5278446 or 5277972 or 5279029 or 5281849 or 5294897 or 5327008 or 5332864 or 5336931 or 5335771 or 5343076 or 5358905 or 5365106 or 5381042 or 5391439 or 5406124 or 5410180 or 5414299 or 5424576 or 5428248 or 5435057 or 5444301 or 5452511 or 5454905 or 5474958 or 5484274 or 5493151 or 5508556 or 5517056 or 5521429 or 5528076 or 5534467 or 5539251 or 5543657 or 5545923 or 5544412 or 5581122 or 5592025 or 5592019 or 5594274 or 5595934 or 5604376 or 5608267 or 5625222 or 5633528).pn.						
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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Signature

Examiner Name	Date